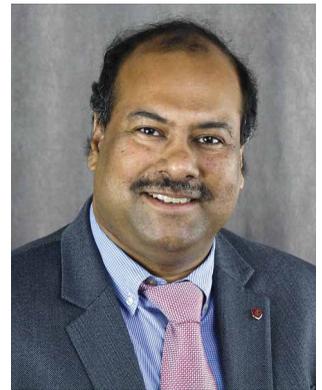


## From the EIC



# Special Issue on Emerging Challenges With 3-D NAND Flash Storage

■ **THE ARTICLE IN** this issue are divided into two groups: 1) the first group comprises the Special Issue on Emerging Challenges With 3-D NAND Flash Storage and 2) the second group consists of general interest articles. In addition, this issue has two conference reports and The Last Byte article.

The highlight of this issue is the Special Issue on Emerging Challenges With 3-D NAND Flash Storage. 3-D NAND flash storage is a very timely topic for both industry and academia, and there are many challenges that span the entire silicon ecosystem from technology, foundry, design, EDA, and test to in-field deployment, and integration into IoT, CPS, edge, and cloud solutions. This special issue aims to introduce the design and test community to emerging challenges with 3-D NAND flash storage. The special issue consists of four research papers and one survey paper. We thank the guest editors, Biswajit Ray, Shyam Raghunathan, and Sudeep Pasricha, for making this special issue possible.

In addition, we have two general interest articles in this issue. The general interest articles are titled as follows: 1) “RF Leakage in Embedded Devices: Security and Reliability Risks” and 2) “SoC-GPIO-Based Dynamic Power Noise Control for Video Sensor Applications.”

This issue also consists of the ISLPED 2025 and ESWEEK 2025 conference reports.

Many thanks to Scott Davidson for The Last Byte article titled “On the Origin of AI Species.”

■ **I HOPE YOU** enjoy reading this issue of *IEEE Design&Test*. ■

A handwritten signature in black ink, appearing to read 'Partha' followed by a stylized surname.

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